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Amend B
KT
8/8/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/827,248
Filing Date April 4, 2001
Inventor David R. Hembree
Assignee Micron Technology, Inc.
Group Art Unit 2829
Examiner V. Nguyen
Attorney's Docket No. MI22-1684
Title: Methods of Processing Wafers and Methods of Communicating Signals With
Respect to a Wafer

RESPONSE TO MARCH 27, 2002 OFFICE ACTION

To: Assistant Commissioner for Patents
Washington, D.C. 20231

EVO 773339

From: James D. Shaurette (Tel. 509-624-4276; Fax 509-838-3424)
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Sir:

Responsive to the Office Action dated March 27, 2002, Applicant amends and
remarks as follows:

AMENDMENTS

In the Abstract

Please insert the following in place of the originally filed Abstract:

B1
--An electronic device workpiece processing apparatus and method of
communicating signals within an electronic device workpiece processing apparatus are
provided. One embodiment of an electronic device workpiece processing apparatus
includes a chuck including a surface, an electrical coupling adjacent the surface, and
electrical interconnect configured to connect with the electrical coupling of the chuck and

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